MEDER electronic
Products for tomorrow...

Europe: +49 / 7731 8399 0 | Email: info@meder.com
USA: +1 / 508 295 0771 | Email: salesusa@meder.com
Asia: +852 / 2955 1682 | Email: salesasia@meder.com

Item No.:
9605010500
Item:
RM05-4-BV10500

DIMENSIONS (mm)

Pinout (Bottom)

Grid spacing is 1.0 mm

Schematic (Top view)
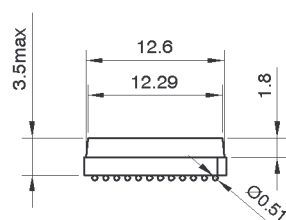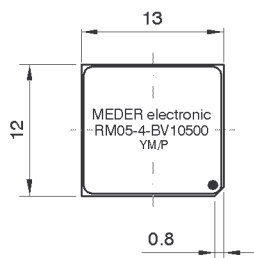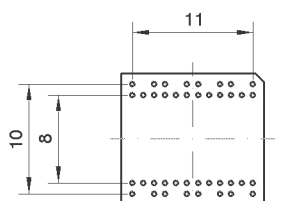
MARKING
MEDER-Label, Type
Production code
EN60062/Factory code
Marking with point

*MEDER-Logo, Typ
Produktionscode,
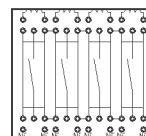EN60062/Betriebsstätte
Markierung mit Punkt*

BGA SOLDER INTERCONNECT
Sn63/Pb37, Ø0.5 mm

MATERIAL of SUBSTRATE
FR4, TG170°C

unspecified tolerances acc. to DIN ISO 2768-f

Coil Data at 20 °C	Conditions	Min	Typ	Max	Unit
Coil resistance		166,5	185	203,5	Ohm
Coil voltage			5		VDC
Rated power			135		mW
Pull-In voltage				3,75	VDC
Drop-Out voltage		0,5			VDC

Contact data 80	Conditions	Min	Typ	Max	Unit
Contact-No.			80		
Contact-form			A		
Contact-rating	Any DC combination of V & A not to exceed their individual max.'s			10	W
Switching voltage	DC or Peak AC			170	V
Switching current	DC or Peak AC			0,5	A
Carry current	DC or Peak AC			0,5	A
Contact resistance static	Measured with 40% overdrive Start Value			200	mOhm
Contact resistance dynamic	Maximum value 1,5 ms after excitation Start Value			250	mOhm
Insulation resistance	RH <45 %, 100 V test voltage	1			GOhm
Breakdown voltage	according to EN 60255-5	210			VDC
Operate time incl. bounce	measured with 40% overdrive			0,1	ms
Release time	measured with no coil excitation			0,02	ms

Special Product Data	Conditions	Min	Typ	Max	Unit
Housing material			mineral filled epoxy		
Material of Substrate			FR4, TG170°C		
Connection pins			BGA Sn63/Pb37		
number of contacts			4		

Environmental data	Conditions	Min	Typ	Max	Unit
Shock	1/2 sine wave duration 11ms			50	g
Vibration	from 10 - 2000 Hz			10	g
Ambient temperature		-40		85	°C
Storage temperature		-55		125	°C
Soldering temperature	JEDEC Norm JESD22-A113A	190		260	°C
Cleaning			fully sealed		